POLYGLASS ASPHALT COVERBOARDS

Due to raw material shortages and long lead times with numerous types of insulation boards, re-cover solutions have become more creative than ever to keep projects moving forward. Polyboard W is an excellent recovery solution for aging BUR/Mod-Bit systems. Polyboard W is a semi rigid, 1/4", 3/16" or 1/8" thick and 40" x 80" panel, composed of an asphaltic core formed between two asphalt-saturated fiberglass liners with multiple bottom and top surface options that boasts the following benefits:

POLYBOARD W

- Sand or film bottom surface boards, attachment methods over existing BUR/Mod-Bit: hot asphalt, foam adhesive, or mechanically attached*
- Polyglass APP**/SBS membranes can be applied over Polyboard W the following ways:
 - -Heat-weld (film surface board)
 - -Hot-mop or cold-apply (sand surface board)
 - -Self-adhere (release film surface board)
- High wind and fire ratings in assemblies using hot asphalt; creates a strong bond with the asphalt saturated Polyboard W
 facer, minimizes need for priming in most applications
- Dimensional stability and superior compressive strength provides additional puncture resistance and strengthens the existing roofing systems.

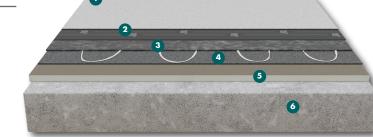
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Typical Recover System with Mechanical Attachment

- 1. Polyglass APP/SBS Cap Sheet TORCH APPLIED
- 2. Polyglass APP/SBS Base/Ply Sheet TORCH APPLIED
- Polyboard W MECHANICALLY ATTACHED (SAND OR FILM BOTTOM, FILM TOP SURFACE)
- 4. Existing BUR/Mod-Bit system
- 5. Existing Insulation
- 6. Approved Substrate

Typical Recover System using Insulation Adhesive

- 1. Polyglass APP/SBS Cap sheet membrane SELF-ADHERED
- 2. Polyglass APP/SBS Base sheet SELF-ADHERED
- Polyboard W Adhered with LRF Adhesive or hot asphalt (sand bottom, release film top surface)
- 4. Existing BUR/Mod Bit System
- 5. Existing Insulation
- 6. Approved Substrate



*Applications may require moisture scans of existing roofing system. Bottom surface must be sand for LRF adhesive applications. **Polyglass APP Membranes are only available for Heat-Welded or Self-Adhered applications